1. Record Nr. UNINA9911020157903321 Autore Enz Christian Titolo Charge-based MOS transistor modeling: the EKV model for low-power and RF IC design / / Christian C. Enz, Eric A. Vittoz Chichester, England;; Hoboken, NJ,: John Wiley, c2006 Pubbl/distr/stampa **ISBN** 9786610649938 9781280649936 1280649933 9780470855461 0470855460 9780470855454 0470855452 Descrizione fisica 1 online resource (329 p.) VittozEric A. <1938-> Altri autori (Persone) 621.3815/284 Disciplina Soggetti Metal oxide semiconductors - Mathematical models Metal oxide semiconductor field-effect transistors - Mathematical models Lingua di pubblicazione Inglese **Formato** Materiale a stampa Livello bibliografico Monografia Note generali Description based upon print version of record. Nota di bibliografia Includes bibliographical references (p. [291]-298) and index. Nota di contenuto Charge-based MOS Transistor Modeling; Contents; Foreword; Preface; List of Symbols; 1 Introduction; 1.1 The Importance of Device Modeling for IC Design; 1.2 A Short History of the EKV MOS Transistor Model; 1.3 The Book Structure: Part I The Basic Long-Channel Intrinsic Charge-Based Model; 2 Definitions; 2.1 The N-channel Transistor Structure; 2.2 Definition of Charges, Current, Potential, and Electric Fields; 2.3 Transistor Symbol and P-Channel Transistor; 3 The Basic Charge Model; 3.1 Poisson's Equation and Gradual Channel Approximation; 3.2 Surface Potential as a Function of Gate Voltage 3.3 Gate Capacitance 3.4 Charge Sheet Approximation: 3.5 Density of Mobile Inverted Charge: 3.5.1 Mobile Charge as a Function of Gate Voltage and Surface Potential; 3.5.2 Mobile Charge as a Function of

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## Sommario/riassunto

Modern, large-scale analog integrated circuits (ICs) are essentially composed of metal-oxide semiconductor (MOS) transistors and their interconnections. As technology scales down to deep sub-micron dimensions and supply voltage decreases to reduce power consumption, these complex analog circuits are even more dependent on the exact behavior of each transistor. High-performance analog circuit design requires a very detailed model of the transistor, describing accurately its static and dynamic behaviors, its noise and matching limitations and its temperature variations. The charge-based EKV (Enz